

ITL Part Code - CU100



Specification

Material: OFHC Copper

Oxygen free high conductivity (OFHC) copper is a suitable sealing material for bakeable UHV systems because of its good conformity with the thermal expansion coefficient of stainless steel as well as its essentially lower hardness (approx. 85 Brinell).

<i>For Flange OD</i>	<i>D1</i>	<i>D2</i>	<i>Pack size</i>
152 (6.00)	120 (4.72)	101 (3.98)	10

